



Multi-Layer, Multi-Material Additive Jettable Inks

Silver Conductive Inks



Highest Conductivity

Conductive performance near the bulk of silver conductivity – resistivity in the range of $10^{-8} \Omega \cdot M$.



Lowest Sintering Temp

Sintering efficiency as low as 8°C in minutes.



Particle-Free Formulation

Jetting reliability particle-free formulation won't clog heads and does not require recirculation.

Flexibility

Flexible and non-brittle with excellent elongation.



Print Compatibility

Viscosity tuned for ElectroJet[™] brand ElectroUV3D[™] printer or other industrybranded heads and printers such as Ricoh, Konica-Minolta, Fuji, and Xaar.

Dielectric Insulating Inks



Dielectric Performance

Superior insulating performance when sandwiched between conductive layers, ensuring efficient electrical insulation.



Adhesion Promotion

Applied as a base layer to optimize adhesion to low surface energy substrates.



Print Enhancements

Provide optimal surface properties for conductive ink holdout and image resolution.



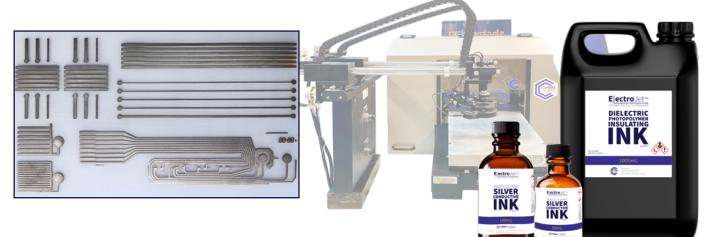
Protective Encapsulation

protects conductive traces from moisture, chemicals, and physical abrasion of the external environment.



Print Compatibility

Viscosity tuned for ElectroJet[™] brand ElectroUV3D[™] printer or other industrybranded heads and printers such as Ricoh, Konica-Minolta, Fuji, and Xaar.



Name/#	Description	Key Features	Resistivity	Sintering
C3-Ag-1037-2	Ethanol-based silver conductive ink for the ElectroUV3D inkjet printer	Low sintering temperature particle-free silver conductive material formulated for piezo inkjet heads	Range 10⁻ [®] Ω•M	80°C
C3-Ag-1037-2h	Ethanol-based silver conductive ink, tuned viscosity for industrial inkjet specifications	Low sintering temperature particle-free silver conductive material formulated for piezo inkjet heads	Range 10⁻ [®] Ω•M	80°C
C3-Cu-100	Copper conductive ink for the ElectroUV3D inkjet printer	Copper conductive material formulated for piezo inkjet heads	2 - 10 x 10 ⁻⁷ Ω•M*	180°C
C3-DI-7	UV curable dielectric insulating ink for the ElectroUV3D inkjet printer	Insulating / building material with excellent adhesion promotion for substrates and compatibility with silver conductive material	3.3 x 10 ¹³ Ω•cm	UV
C3-DI-7h	UV curable dielectric insulating ink, tuned viscosity for industrial inkjet specifications	Insulating / building material with excellent adhesion promotion for substrates and compatibility with silver conductive material	3.3 x 10 ¹³ Ω•cm	UV
C3-DI-HF-27	UV curable low loss, high frequency dielectric insulating ink for the ElectroUV3D inkjet printer	High frequency insulating / building material with excellent adhesion promotion for substrates and compatibility with silver conductive material	N/A	UV
С3-ОРТ-7	Optically clear UV curable dielectric insulating ink for the ElectroUV3D inkjet printer	Transparent insulating / building material with excellent insulating properties for higher voltage and compatibility with silver conductive material	3.3 x 10 ¹³ Ω•cm	UV
C3-OPT-7h	Optically clear UV curable dielectric insulating ink, tuned viscosity for industrial inkjet specifications	Transparent insulating / building material with excellent insulating properties for higher voltage and compatibility with silver conductive material	3.3 x 10 ¹³ Ω•cm	UV
C3-DI-8	Flexible UV curable dielectric insulating ink for the ElectroUV3D inkjet printer	Insulating / building material for interlayer insulation optimized for flexible circuitry and compatibility with silver conductive material	3.3 x 10 ¹³ Ω•cm	UV
C3-DI-8h	Flexible UV curable dielectric insulating ink, tuned viscosity for industrial inkjet specifications	Insulating / building material for interlayer insulation optimized for flexible circuitry and compatibility with silver conductive material	3.3 x 10 ¹³ Ω•cm	UV
C3-DI-CNT-6	High-performance dielectric ink for the ElectroUV3D inkjet printer in conjunction with C3-DI-7	Makes C3-DI-7 3x stronger, withstands much higher tempertures, dramatically small Coefficient of thermal expansion with a lower dielectric constant	N/A	UV
C3-PR-8	A direct chemical adhesion primer solution for LSE surface preparation	Specialized direct chemical adhesion primer solution for high-surface energy substrates optimized for direct print silver conductive ink	N/A	N/A
C3-S	An overnight storage solution for conductive inkjet heads	Maintains the performance and longevity of conductive inkjet heads for consistent printing results over time	N/A	N/A



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